

**Thirteenth World Round Table Conference on Sintering** 

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# Synthesis and Processing of Particulate Materials

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### **University of Trento - Italy**









### **University of Trento - Italy**

Founded in 1962

- 16.000 students (900 PhD students)
- 750 professors
- 750 technicians & administrative staff members
- 11 departments
- 4 research centers





### Processing technologies for ceramic materials



### **Powder metallurgy**

### Near net-shape production of metallic components

#### Advantages:

- Uniform microstructure and distribution of alloying elements
- No machining
- Flexibility in component design

### Disadvantages

- Porosity
- Fatigue and fracture resistance

## Outline

#### Starting from powders: ceramic and metallic powders

- synthesis processes, challenges and issues
- powders from natural sources and wastes

#### Colloidal suspensions and pastes for ceramic production

- deflocculated systems: additives and stability, micro- and nano-powders
- viscous and plastic behaviour

## Conventional shaping methods for powder metallurgy and ceramics; features, shapes and technological issues

- pressing or die-compaction; granulation
- extrusion
- slip and tape casting
- injection moulding

#### Innovative forming methods for ceramics and metals: additive manufacturing

- powder bed fusion, directed energy deposition, binder jetting, direct inkjet printing, fused filament deposition, stereolithography and two-photon polymerization

#### Drying and presintering processes

#### Innovative sintering processes

## **Powder preparation methods for ceramics**

#### **Powder Preparation Method Advantages Disadvantages** Mechanical Inexpensive; wide Limited purity; limited homogeneity; large Comminution μm applicability particle size High-energy ball milling Fine particle size; good for Limited purity; limited homogeneity nonoxides; low temperature route Chemical Solid-state reaction; decomposition; Agglomerated powder; limited homogeneity for Simple equipment; multicomponent powders reaction between solids inexpensive Liquid solutions High purity; small particle Precipitation; coprecipitation; Expensive; limited applicability to nonoxides solvent vaporization (spray drying; size; composition and spray pyrolysis; freeze drying) particle size control Gel routes (sol-gel; Pechini; citrate High purity; good Agglomerated powder; limited control of particle composition control; gel; glycine nitrate) size chemical homogeneity High purity; small particle Limited to nonoxides Nonaqueous liquid reaction size **Vapor-phase reaction** Gas-solid reaction Inexpensive for large particle Low purity; expensive for fine powders size Gas-liquid reaction High purity; small particle Expensive; limited applicability size nm Expensive for nonoxides; agglomeration often a Reaction between gases High purity; small particle size; inexpensive for oxides problem

## **Milling or Comminution**

### Mechanical stresses among particles and sizes









Attrition Mill





#### Commercially Available Grinding Media for Ball Milling

Grinding Media	Density (g/cm <sup>3</sup> )	
Porcelain	2.3	
Silicon nitride	3.1	
Silicon carbide	3.1	
Alumina		
Lower than 95% purity	3.4-3.6	
Higher than 99% purity	3.9	
Zirconia		
MgO stabilized	5.5	
High-purity $Y_2O_3$ stabilized	6.0	
Steel	7.7	
Tungsten carbide	14.5	





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### **Comparison among systems**



Jaw crushers Cone crushers Crushing rolls Hammer mill Jet mill Vibratory mill Ball mill Attrition mill Roller mill

to 5mm to 5mm to ~1mm to ~0.1mm 1 to ~50μm 1 to ~50μm 0.5–10μm 0.1–5μm 0.1–5μm

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## **Chemical methods**

- **Solid state reactions** coarse powders (above 10 μm)

 $SiO_2 + 3C \rightarrow SiC + 2CO$ 

Acheson process (2200-2500°C)







Powders

Partially reacted

Fully reacted

#### **Issues:**

- Homogeneity and size of the starting mix
- Presence of unreacted reagents
- Temperature
- Agglomeration (grinding)



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- **Precipitation from solutions** (by nucleation and growth)

hydrolysis of solutions of metal-organic compounds (see sol-gel) or metal salts

 $Ti(OC_2H_5)_4 + (2+x)H_2O \rightleftharpoons TiO_2.xH_2O + 4C_2H_5OH$  Stober process



coprecipitation of complex oxides

 $Ba(OC_{3}H_{7})_{2} + Ti(OC_{5}H_{11})_{4} + 3H_{2}O \rightarrow BaTiO_{3} + 4C_{5}H_{11}OH + 2C_{3}H_{7}OH$ 

precipitation under hydrothermal conditions (100-374°C, 220 bar)

 $\text{TiO}_2 + \text{Ba(OH)}_2 \rightarrow \text{BaTiO}_3 + \text{H}_2\text{O}$  V.M. Sglavo – UNTN 2024

#### **Issues:**

- Aggregation or agglomeration
- Particles growth by Ostwald ripening

### Sol-gel alkoxides water solution "Sol" $(Si(OR)_4)$ "Gel" glass $\Delta T > 0$ $\Delta T > 0$ $Si(OR)_4 + H_2O$ $(OR)_3Si-OH + Si(OR)_4 \rightarrow (OR)_3Si-O-Si(OR)_3 + ROH$ ceramic $(OR)_3$ Si-OH + ROH $(OR)_3Si-OH + (OR)_3Si-OH \rightarrow (OR)_3Si-O-Si(OR)_3 + H_2O$ **Hydrolysis Condensation**

#### **Typical alkoxides**

Chemical Name formula		Physical state				
Aluminum s-butoxide	$AI(O^{s}C_{4}H_{9})_{3}$	Colorless liq., T <sub>B</sub> ~203°C				
Aluminum ethoxide	$AI(OC_2H_5)_3$	White powder, T <sub>M</sub> 130°C				
Aluminum isopropoxide	AI[O <sup>i</sup> C <sub>3</sub> H <sub>7</sub> ] <sub>3</sub>	White powder, T <sub>M</sub> 118.5°C				
Antimony ethoxide	$Sb(OC_2H_5)_3$	Colorless liq., T <sub>B</sub> 95°C				
Barium isopropoxide	Ba(O <sup>i</sup> C <sub>3</sub> H <sub>7</sub> ) <sub>2</sub>	Off-white powder				
Boron ethoxide	$B(OC_2H_5)_3$	Colorless liq., <i>T</i> <sub>B</sub> 117.4°C				
Calcium methoxide	Ca(OCH <sub>3</sub> ) <sub>2</sub>	Off-white powder				
Iron ethoxide	$Fe(OC_2H_5)_3$	<i>T</i> <sub>M</sub> 120°C				
Iron isopropoxide	Fe(O <sup>i</sup> C <sub>3</sub> H <sub>7</sub> ) <sub>3</sub>	Brown powder				
Silicon tetraethoxide	$Si(OC_2H_5)_4$	Colorless liq., <i>T</i> <sub>B</sub> 165.8°C				
Silicon tetraheptoxide	$Si(OC_7H_{15})_4$	Yellow liq.				
Silicon tetrahexoxide	Si(OC <sub>6</sub> H <sub>13</sub> ) <sub>4</sub>	Colorless liq.				
Silicon tetramethoxide	Si(OCH <sub>3</sub> ) <sub>4</sub>	Colorless liq., T <sub>B</sub> 121–122°C				
Titanium ethoxide	Ti(OC <sub>2</sub> H <sub>5</sub> ) <sub>4</sub>	Colorless liq., <i>T</i> <sub>B</sub> 122°C				
Titanium isopropoxide	Ti[O <sup>/</sup> C <sub>3</sub> H <sub>7</sub> ] <sub>4</sub>	Colorless liq., T <sub>B</sub> 58°C				
Yttrium isopropoxide	Y[O <sup>′</sup> C <sub>3</sub> H <sub>7</sub> ] <sub>3</sub>	Yellowish-brown liq.				



#### **Examples of solution formulations**

	One component: 100 mol% SiO <sub>2</sub>			Two components: 94 mol% SiO <sub>2</sub> + 6 mol % TiO <sub>2</sub>			Three components: 15 mol% $Li_2O + 3$ mol% $Al_2O_3 + 82$ mol% $SiO_2$						
	Soln. conc.	Oxide content			Soln. conc.	Oxide content			Soln. conc.	Oxide			_
Precursor	wt%/100 g	vol%/ 100 mL	mol	g/mol	wt%/100 g	vol%/ 100 mL	mol g	g/mol	wt%/100 g 1	vol%/ 100 mL	mol	g/mol	_
Si(OC <sub>2</sub> H <sub>5</sub> ) <sub>4</sub> Ti(OC <sub>3</sub> H <sub>7</sub> ) <sub>4</sub>	45	43		V.ſ	<b>11. S</b>	glav	0\	_ [	35	34	20	)24	4
AI(OC <sub>4</sub> H <sub>9</sub> ) <sub>3</sub>									1	1			
	40	43	4		36	41	14		3 29	1 34	4		
H <sub>2</sub> O	16	14	4		52	47	50		33	30	8		
Öxide (Si + Ti + Al + Li)			1	11.3			1 :	3.15			1	10.6	

#### **Process scheme**



#### Acidic-catalysis







- Spray pyrolysis

solution (see also sol-gel) sprayed in hot and oxidizing atmosphere















### - Gel routes

starting from a gel or viscous resin

- sol-gel (the gel is dried and crashed)
- Pechini method (polyesterification induced by ethylene glycol addition)
- citrate method
- glycine method



SrTiO<sub>3</sub> by Pechini method



### - Gas – solid reaction

- nitrididation for  $Si_3N_4$  (from Si powder)

- carbothermal reduction

 $3SiO_2 + 6C + 2N_2 \rightarrow Si_3N_4 + 6CO$ 

() () () () O(g)



## Powder from natural sources or wastes



## **Powder preparation methods for metals**

- Mechanical
  - Machining
- limited purity and homogeneity
- Milling
- Mechanical alloying
- Cold stream process

### • Chemical

- Electrolytic deposition
- Decomposition of a solid by a gas
- Thermal decomposition
- Precipitation from a liquid
- Precipitation from a gas
- Solid-solid reactive synthesis

### • Physical

Atomization techniques



### **Cold stream process**









#### Ceramic tube cross section







### Thermochemical reduction routes to produce titanium









Cathod:  $[0]_{\text{Tio}_2} + e^- \rightarrow 0^{2-}$ 

in molten CaCl<sub>2</sub> (800-1100°C)



### Water atomization



SEM, 300×

Surface oxidation!

### **Gas atomization**





### **Vacuum atomization**



The melt is pressurized with hydrogen (1–3 MPa) and then released into vacuum



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### Plasma rotating electrode process







Ti-6Al-4V

SEM,  $100 \times$ 

## **Powder characteristics for the green compact**

Aspect # 1: packing factor ٠

for particles of the same size

dense packing: *loose packing:* PF = 0.57-0.61

PF = 0.635 - 0.64

### shape effect

Particle Shape	Aspect Ratio	Packing Density	07		
Sphere	1	0.64	0.7		$\bigcirc$
Cube	1	0.75		$\bigcup$	
Rectangle	2:5:10	0.51	₹ 06 L		
Plate	1:4:4	0.67	ensi	$\wedge$	$\bigcirc$ $\neg$
Plate	1:8:8	0.59	lg de		
Cyclinder	5	0.52	ckin	$\lambda \times \langle \rangle$	
Cyclinder	15	0.28	в 0.5 <b>–</b>		
Cyclinder	60	0.09		1/53	
Disk	0.5	0.63		Y V	
Tetrahedron	1	0.5	0.4	05	]

**Relative roundness** 

### for particles with different size





 $a_c/a_F = 2.4/1$   $a_c/a_F = 6.5/1$   $a_c/a_F = 10/1$ 

### best condition: $15 > a_c/a_f > 7$



## 12024

• Aspect # 2: alloying in PM



Blend of elemental powders



Partial alloying by diffusion



Prealloying

1



Coated powders



Blend of elemental powders and master alloy







suspension = biphasic system constituted by a liquid and a solid

### **Possible configurations**

Agglomeration

**Stabilization** 



rigid system



plastic (deformable) system

# **Double electrical layer**

the majority of the systems are negatively charged on the surface





### $\kappa^{-1}$ = distance at which $\psi = \psi_0/2.718$ = Debye length ( $\kappa =$

### $(\kappa = Debye$ -Huckel parameter)



 $N_{i}$ ,  $Z_i$  = molarity and valence of any ion type in the solution

Faraday constant  $F = N_A e^2 = 9.649 \times 10^4 \text{ C mol}^{-1}$ 

Permittivity of vacuum  $\varepsilon_0 = 8.854 \text{ x } 10^{-12} \text{ C}^2 \text{ J}^{-1} \text{ m}^{-1}$ 

Boltzman constant  $k_B = 1.381 \ge 10^{-23} \text{ J K}^{-1}$ 

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## Zeta potential

 $\zeta$  = electrical potential on the shear plane



Compound		Dielectric Constant	Compou	Dielectric	
Hydrogen-bondi	ng		Non-hydrogen bo	nding	
methyl-	-		Acetone	(CH <sub>3</sub> ) <sub>2</sub> CO	20.7
formamide	HCONHCH <sub>3</sub>	182.4	Chloroform	CHCl <sub>3</sub>	5.0
Formamide	HCONH,	109.5	Benzene	C <sub>6</sub> H <sub>6</sub>	2.3
Hydrogen	-		Carbon		
fluoride	HF	84"	tetrachloride	CCl₄	2.2
Water	H,O	78.5	Cyclohexane	C <sub>6</sub> H <sub>12</sub>	2.0
Formic acid	нсоон	58.5	Dodecane	C12H26	2.0
Ethylene			Hexane	C <sub>6</sub> H <sub>14</sub>	1.9
glycol	$C_{2}H_{4}(OH)_{2}$	40.7	Crystals		
Methanol	CH,OH	32.6	Sodium		
Ethanol	C,H,OH	24.3	chloride	NaCl	6.0
n-Propanol	C <sub>3</sub> H <sub>7</sub> OH	20.2	Diamond	C	5.7
Ammonia	NH <sub>3</sub>	16.9	Quartz	SiO.	4.5
Acetic acid	CH <sub>3</sub> COOH	6.2	Quarte	0.01	1.0



the zeta potenzial, ζ, is an index of the electrical potential (ψ) gradient



• *influence of ions in solution* 

![](_page_46_Figure_1.jpeg)

- if N increases  $\kappa^{-1}$  decreases
  - and  $\zeta$  decreases, too
- if Z increases  $\kappa^{-1}$  decreases

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## Surface charge origin

• desorption & dissolution of ions (clays – isomorphic substitution of Si & Al)

![](_page_47_Figure_2.jpeg)

![](_page_47_Figure_3.jpeg)

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• chemical reactions with aqueous medium

$$\text{MOH}_{(\text{surface})} + \text{H}^{+}_{(\text{solution})} \stackrel{K_1}{\longleftrightarrow} \text{MOH}_2^{+}_{(\text{surface})}$$

$$\text{MOH}_{(\text{surface})} \overleftrightarrow{K_2}^{\text{MO}^-}_{(\text{surface})} + \text{H}^+_{(\text{solution})}$$

![](_page_48_Picture_3.jpeg)

### Example: alumina

![](_page_48_Figure_5.jpeg)

# point of zero charge = PZC = $\frac{pK_1^{-1} + pK_2}{2}$ = isoelectric point = IEP

acid-base character of the surface (K<sub>1</sub> and K<sub>2</sub> depend on the material)

![](_page_49_Figure_2.jpeg)

SiO<sub>2</sub>

*IEP = 2* 

Si--ОН

Si-OH

Si--OH

si-/-он

SiO<sub>2</sub> particle

pH < 2

pH > 2

solution

"basic" solution

Si-OH2

Si-OH2

Si-OH

 $-OH_2^+$ 

 $+ H_2O$ 

Material	Nominal Composition	IEP
Muscovite	$KAl_3Si_3O_{11} \cdot H_2O$	1
Quartz	SiO <sub>2</sub>	2
Delta manganese oxide	$MnO_2$	2
Soda lime silica glass	$1.00Na_2O \cdot 0.58CaO \cdot 3.70SiO_2$	2-3
Albite	$Na_2O \cdot Al_2O_3 \cdot 6SiO_2$	2
Orthoclase	$K_2O \cdot Al_2O_3 \cdot 6SiO_2$	3-5
Silica (amorphous)	SiO <sub>2</sub>	3-4
Zirconia	ZrO <sub>2</sub>	4-5
Rutile	TiO <sub>2</sub>	4–5
Tin Oxide	SnO <sub>2</sub>	4–7
Apatite	$10CaO \cdot 6PO_2 \cdot 2H_2O$	4-6
Zircon	$SiO_2 \cdot ZrO_2$	5-6
Anatase	TiO <sub>2</sub>	6
Magnetite	Fe <sub>3</sub> O <sub>4</sub>	6–7
Hematite	$\alpha Fe_2O_3$	6–9
Goethite	FeOOH	6-7
Gamma iron oxide	$\gamma Fe_2O_3$	6-7
Kaolin (edges)	$Al_2O_3 \cdot SiO_2 \cdot 2H_2O$	6-7
Chromium oxide	$\alpha Cr_2O_3$	6-7
Mullite	$3Al_2O_3 \cdot 2SiO_2$	7-8
Gamma alumina	$\gamma Al_2O_3$	7–9
Alpha alumina	$\alpha Al_2O_3$	9-9.5
Alumina (Bayer process)	$Al_2O_3$	7-9.5
Zinc oxide	ZnO <sub>2</sub>	9
Copper oxide	CuO	9
Barium carbonate	BaCO <sub>3</sub>	10-11
Yttria	$Y_2O_3$	11
Lanthanum oxide	$La_2O_3$	10-12
Silver oxide	Ag <sub>2</sub> O	11-12
Magnesium Oxide	MgO	12-13

![](_page_50_Figure_1.jpeg)

## **Stability of suspensions**

interaction between two colloidal particles in suspension

DLVO (Derjaguin e Landau / Verweij e Overbeek) theory

attraction: Van del Waals force

 $A_h = Hamaker \text{ constant} \approx 10^{-20} \text{ J}$ 

 $U_{A} = \frac{-A_{h}R}{12H} \qquad F_{A} = \frac{-A_{h}R}{12H^{2}}$ 

**repulsion:** *interaction between double electrical layers* 

$$U_{R} = 2\pi\varepsilon\varepsilon_{0} R\psi_{0}^{2} e^{-\left(\frac{H}{\kappa^{-1}}\right)} \qquad R/\kappa^{1} < 5$$

$$F_{R} = \frac{2\pi\varepsilon\varepsilon_{0}R\psi_{0}^{2}}{\kappa^{-1}}e^{-\left(\frac{H}{\kappa^{-1}}\right)}$$

![](_page_51_Picture_9.jpeg)

 $\mathbf{U}_{\mathrm{T}} = \mathbf{U}_{\mathrm{A}} + \mathbf{U}_{\mathrm{R}}$ 

![](_page_52_Figure_1.jpeg)

![](_page_53_Figure_0.jpeg)

### **Coagulation** (not desired in ceramic systems!)

- $\zeta < 20 \text{ mV}$  (Brownian motions)
- presence of ions:  $Li^+ > Na^+ > K^+ > NH_4^+$

 $Mg^{2+} > Ca^{2+} > Sr^{2+} > Ba^{2+}$  $I^{-} > SO_4^{2-} > Cl^{-} > F^{-} > NO_3^{-}$ 

coagulation power

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solvation cloud + polarizability

Ion	Radius (Å)	Hydration (mol H <sub>2</sub> O)	Hydrated Radius (Å)	
Li <sup>+</sup>	0.78	14	7.3	K*
Na <sup>+</sup>	0.98	10	5.6	
K <sup>+</sup>	1.33	6	3.8	
Rb <sup>+</sup>	1.49	0.5	3.6	
$NH_4^+$	1.43	3	_	+
Mg <sup>2+</sup>	0.78	22	10.8	adsorbtion tendency
Ca <sup>2+</sup>	1.06	20	9.6	
Ba <sup>2+</sup>	1.43	19	8.8	
$Al^{3+}$	0.57	57		

### coagulant agents

CaCl<sub>2</sub>, CaCO<sub>3</sub>, MgCl<sub>2</sub>, MgSO<sub>4</sub>, FeCl<sub>3</sub>, AlCl<sub>3</sub>

### **Deflocculation – stabilization of colloidal suspensions**

![](_page_55_Picture_1.jpeg)

![](_page_55_Picture_2.jpeg)

![](_page_55_Picture_3.jpeg)

• *electrostatic stabilization when*  $\zeta > 20 \text{ mV}$ 

• *steric stabilization* adsorbtion of polymers/surfactants

![](_page_55_Picture_6.jpeg)

#### electrostatic stabilization

![](_page_56_Figure_1.jpeg)

### *steric stabilization:* adsorbtion of specific polymers /surfactants with high MW (>10<sup>6</sup>)

![](_page_57_Figure_1.jpeg)

Aq	ueous dispersions	1 238
Anchor polymer	Stabilizing moieties	
polystyrene poly(vinyl acetate) poly(methyl methacrylate) poly(acrylonitrile) poly(dimethylsiloxane) poly(vinyl chloride) poly(ethylene) poly(propylene) poly(lauryl methacrylate)	poly(oxyethylene) poly(vinyl alcohol) poly(acrylic acid) poly(methacrylic acid) poly(acrylamide) poly(vinyl pyrrolidone) poly(vinyl pyrrolidone) poly(ethylene imine) poly(vinyl methyl ether) poly(4-vinylpyridine)	O S O S O
Nona Ancher polymer	iqueous dispersions Stabilizing maiaties	
poly(acrylonitrile) poly(oxyethylene) poly(ethylene) poly(propylene) poly(vinyl chloride) poly(methyl methacrylate) poly(acrylamide)	polystyrene poly(lauryl methacrylate) poly(12-hydroxystearic acid) poly(dimethylsiloxane) poly(isobutylene) cis-1:4-poly(isoprene) poly(vinyl acetate) poly(winyl methacrylate) poly(vinyl methyl ether)	UNITN 2024

### *electrosteric stabilization:* adsorbtion of ions / polyelectrolites

![](_page_59_Figure_1.jpeg)

Sodium Polyacrylate

Sodium Pyrophosphate

![](_page_59_Picture_4.jpeg)

### deflocculant agents

Inorganic	Organic		
Sodium carbonate	Sodium polymethacrylate		
Sodium silicate	Ammonium polyacrylate		
Sodium borate	Sodium citrate		
Tetrasodium pyrophosphate	Sodium succinate		
	Sodium tartrate		
	Sodium polysulfonate		
	Ammonium citrate		

X=Na, K, NH <sub>4</sub>
$\begin{bmatrix} 0 x^+ & 0 x^+ \\ -0 -s_j - 0 - s_j - 0 \\ 0 x^+ & 0 x^+ \end{bmatrix}_n$
$\begin{bmatrix} 0 & 0 \\ 0 & 0 \\ -0 - P & -0 \\ 0 \\ 0 \\ x^{+} & 0 \end{bmatrix}_{n}$

Organic dispersing agents	X=Na, K, NH <sub>4</sub> ; R=C <sub>k</sub> H <sub>2k+1</sub> with k=0,1,2,3,	
Polycarbonate	$\begin{bmatrix} R & Q \\ c \\ R & -C \\ R & C \\ R & C$	
Polyacrylate (k=0) and -methacrylate (k=1,2,3,)	$ \begin{bmatrix} H & R & H & COOX^{*} \\ -C & C & C & -C \\ -C & -C &$	
Oxalate	-xo_cox.	
Citrate	-xo H COOX. H O VO C H COOX. H C O V O V	
Alcanolamines (Aminoalcohols)	$H \xrightarrow{H} C \xrightarrow{R} I \xrightarrow{-H} H$	

# **Slurries and pastes**

- powder
- solvent
- dispersant
- binder
- plasticizer
- lubricant
- others

Forming Method	Solvent	Dispersant	Binder	Plasticizer	Other Additives		
Dry Pressing							
Die compaction	-	<u> </u>	<5	<2-3	<1ª		
Isostatic compaction		<u> </u>	<5	—	—		
		Slurry-Ba	sed Methods				
Slip casting	50-60	< 0.5-2	< 0.5-1	—	—		
Tape casting	50-60	<0.5-2	10-15	5-10	<1-2 <sup>b</sup>		
		Plastic For	ming Method	ls			
Extrusion	30-40	< 0.5-2	5	1	<1-2 <sup>a</sup>		
Injection molding	—	—	25-30	5-10	<2-5ª		
<ul> <li>Note: The actual concentration in a given forming method can vary widely, depending on factors such as the particle size of the powder and the composition and molecular weight of the additive.</li> <li><sup>a</sup> Lubricant.</li> <li><sup>b</sup> Wetting agent; homogenizer; antifoaming agent.</li> </ul>							

![](_page_61_Picture_9.jpeg)

# **Rheology of ceramic systems**

system	reology	DPS
powder	elastic	0
granulated powder	elasto-plastic	<<1
paste or plastic mix	elasto-plastic	<1
slurry	viscous	>1

DPS = degree of pore saturation = volume of liquid / volume of pores

![](_page_62_Picture_3.jpeg)

*DPS* < 1

elasto-plastic behaviour

• **interaction among particles** (friction ↔ lubricant)

![](_page_63_Figure_3.jpeg)

![](_page_64_Figure_0.jpeg)

![](_page_65_Figure_0.jpeg)

# Forming technologies from powders

![](_page_66_Figure_1.jpeg)

- granulated powder

![](_page_66_Figure_3.jpeg)

- extrusion, injection moulding
- ceramic paste

- tape casting, slip casting
- ceramic suspension

![](_page_66_Figure_8.jpeg)

![](_page_67_Figure_0.jpeg)

# Granulation

• direct granulation (pellettization)

![](_page_68_Figure_2.jpeg)

![](_page_68_Picture_3.jpeg)

irregular shapes and distributed sizes

### • spray drying

![](_page_69_Figure_1.jpeg)

![](_page_69_Picture_2.jpeg)

regular shapes and well distributed sizes

![](_page_69_Figure_4.jpeg)

![](_page_70_Figure_0.jpeg)

![](_page_71_Figure_0.jpeg)

segmented dies for complicated shapes
#### additives

Product	Binder	Plasticizer	Lubricant
Alumina	Polyvinyl alcohol	Polyethylene glycol	Mg Stearate
96% alumina substrates	Polyethylene glycol	None	Talc, clay
Alumina spark plug insulation	Microcrystalline wax emulsion	KOH + tannic acid	Wax, talc clay
MnZn Ferrites	Polyvinyl alcohol	Polyethylene glycol	Zn Stearate
Ba Titanate	Polyvinyl alcohol	Polyethylene glycol	
Steatite	Microcrystalline wax, clay	Water	Wax, talc, clay
Ceramic tile	Clay	Water	Talc, clay
Hotel china	Clay, polysaccharide	Water	Clay
Refractories	Ca/Na lignosulfonate	Water	Stearate



#### granules

	Particle Size <sup>a</sup> (µm)	Organics (vol%)	Granule Size <sup>b</sup> (µm)	Granule Density (%)	Fill Density (%)
Alumina substrate	0.7	3.6	92	54	32
Spark plug alumina	2.0	13.3	186	55	34
Zirconia sensor	1.0	10.5	75	55	37
MnZn ferrite <sup>c</sup>	0.7	10.0	53	$55^d$	32
MnZn ferrite <sup>e</sup>	0.2	8.5	56	31	18
Silicon carbide	0.3	20.4	174	45	29
		Water (vol%)	)		
Wall tile	9	13-21	134		38

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#### **Pressing & density**





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#### pressing of 3 mol% $Y_2O_3$ – 97 mol% $ZrO_2$ granules



(c). 70MPa.

04//42 100-

(a). 90MPa.

*Figura* 7(*a*), (*b*), (*c*) *e* (*d*). *Fotografie ottenute dal SEM con ingrandimento* 100*x*.



#### density gradients:

- absence of lubricant (B, C)
- uneven filling (B)
- L/D > 2 (A, B)
- too high compaction (*spingback*) (A, B, C)



Α



С



В

D <----> ∧ L v OK



# **Slip casting**



#### porous mould

• plaster of Paris - CaSO<sub>4</sub>2H<sub>2</sub>O -

#### • polymeric resin

porosity = 40-50%max pore size  $\approx 5 \ \mu m$ 

	Concentrat	tion (vol%)	
Material	Porcelain	Alumina	
Alumina		40-50	
Silica	10-15		
Feldspar	10-15		
Clay	15-25		
Water	45-60	50-60	
	100 vol%	100 vol%	
Processing additives (wt% <sup>a</sup> )			
Deflocculant			
Na silicate	< 0.5		
NH <sub>4</sub> polyacrylate		0.5-2	
Na citrate		0.0-0.5	
Coagulant			
CaCO <sub>3</sub>	< 0.1		
BaCO <sub>3</sub>	< 0.1		
Binder			
Na carboxymethylcellulose		0.0-0.5	





#### hollow bodies







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#### Formation of the "cake"



### Pressure casting



Pressure		Casting Rate (mm <sup>2</sup> /min)		
(kPa)	Porcelain-	Alumina	Alumina	Zirconia
140	2.0	2.4	0.3	
280	3.1	4.9		
560	5.2	10		0.1
1400		25		0.3
2800		50		0.8



+0.5 wt% PVA binder

# **Tape casting**





#### suspensions

Al <sub>2</sub> O <sub>3</sub> powder	Matrix	40 -50	1
MgO powder	Grain growth inhibitor	0,5 - 3	
Destilled water	Solvent	30 - 50	8
Polyvinylacetate	Binder	5 - 10	
Polyethylenglykol	Plasticizer	0,5 - 3	
Dibutylphthalate	Plasticizer	0,5 - 3	
Arylic sulphuric acid	Deflocculant	0,1 - 0,3	
Octylphenoxyethanol	Wetting agent	0,1 - 0,3	

Matrix	40 – 50
Solvent	15 - 25
Solvent	15 - 25
Binder	5 - 10
Plasticizer	0,5 - 3
Plasticizer	0,5 - 3
Deflocculant	0,5 – 3
	Matrix Solvent Solvent Binder Plasticizer Plasticizer Deflocculant

## **Extrusion**





vol	%
-----	---

Silicon Carbide		High Alumina		Electrical Po	Electrical Porcelain	
Silicon carbide Hydroxyethyl	50	Alumina Ball clay	46 4	Quartz powder	16	
cellulose	6	Methyl		Feldspar	16	
Water	42	cellulose	2	Kaolin	16	
Polyethylene glycol	2	Water	48	Ball clay	16	
				Water	36	
				CaCO <sub>3</sub>	<1	

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#### **Pressure distribution and gradients**





- extrusion average velocity
- entrance angle





shear stresses

$$\tau = \frac{r\left(P_1 - P_2\right)}{2L}$$

#### flow velocity gradient













#### gradients $\rightarrow$ defects



# **Injection molding**



#### Examples

Plasticizer

Dimethyl phthalate

Diethyl phthalate

Dibutyl phthalate

Dioctyl phthalate

**Minor Binder** 

Microcrystalline wax

Paraffin wax

Carnauba wax

Major Binder

Poly(methyl methacrylate)

Polypropylene

Poly(vinyl acetate)

Polyethylene

Polystyrene

Component	Composition (wt%)		
Powder	1-µm Al <sub>2</sub> O <sub>3</sub> (85)	20-µm Si (82)	
Major binder	Paraffin wax (14)	Polypropylene (12)	
Minor binder	<u> </u>	Microcrystalline wax (4)	
Other additives	Oleic acid (1)	Stearic acid (2)	

**Other Additives** 

Stearic acid

Organo silane

Organo titanate

Oleic acid

Fish oil

# Additive manufacturing

#### New technologies:

- rapid prototyping
- solid freeform fabrication
- additive manufacturing or three-dimensional (3D) printing





2. CAD file creation

## **3D printing for ceramics**

Feed Material	Method	Process
Powder		
Powder-binder mixture or binder- coated powder	Selective laser sintering (SLS)	Laser beam scanned on layer of material to soften binder and bind particles
Powder or dried powder from a slurry	Three-dimensional printing (3DP)	Binder solution sprayed on powder bed to bind particles
Particle-Filled Polymer		
Particle-filled polymer filaments	Fused deposition modeling (FDM)	Extrusion of softened filaments through a heated nozzle
Tape-cast sheets	Laminated object manufacturing (LOM)	Sheets cut by laser beam and stacked
Suspension, Slurry, or Paste		
Particles dispersed in monomer solution	Stereolithography	Laser beam scanned on suspension to polymerize monomer solution
Moderately dilute suspension stabilized with organic additives	Inkjet printing	Printing of droplets from printer nozzle followed by drying by evaporation
Concentrated slurry or paste stabilized with organic additives	Robocasting	Extrusion of slurry or paste through a nozzle followed by drying or gelation
Concentrated slurry or paste stabilized with organic additives	Freeze extrusion fabrication (FEF)	Extrusion of slurry or paste through a nozzle and freezing in a cold chamber

#### Selective laser sintering





#### **Binder jetting**





#### Fused deposition modeling – fused filament modeling - robocasting







# **3D printing for metals**

Process	Abbreviation	Mode	Typical Applications
Material extrusion	ME	Material is selectively dispensed through a nozzle or orifice	Functional metal parts, prototyping,
Binder jetting	BJ	A liquid bonding agent is selectively deposited to join powder materials	Functional metal parts, low-rate production runs of non-critical components
Directed energy deposition	DED	Focused thermal energy is used to fuse materials by melting as they are being deposited	Functional metal parts, repairs, adding material to existing parts
Powder bed fusion	PBF	Thermal energy selectively fuses regions of a powder bed	Functional metal parts, functional prototyping



#### **Metal extrusion**





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Radii at layer extremity— (stair stepping effect)

#### **Powder bed fusion**



#### **Powder bed fusion**



#### **Directed energy deposition**







## evaporation speed (mass evaporating per unit area x time) $R_E = K_E(p_W - p_0)$ vapour pressure initial pressure of the liquid in the air air flow conditions

#### evaporation heat

Heat of Vaporization (MJ/kg)			
Temperature (°C)	H <sub>2</sub> O	СН <sub>3</sub> ОН	C <sub>2</sub> H <sub>5</sub> OH
20	2.45	1.17	0.91
40	2.40	1.14	0.90
60	2.36	1.11	0.88
80	2.31	1.06	0.85
100	2.26	1.01	0.81
#### surface tension effects

#### bubble in a liquid





#### vapour pressure above the surface





#### shrinkage and stresses upon drying





influence of forming process (DPS value)

 $\frac{\Delta V}{V_0} = 1 - \left[1 - \frac{\Delta L}{L_0}\right]^3$  $\frac{\Delta L}{L_0} = N_p \Delta l$ 

mean number of interparticle liquid films per unit length

mean reduction of interparticle spacing



# **Pre-sintering processes**

#### Thermolysis of organic compounds



Green article surface

slow and uniform removal of the "binders", decomposition/reaction ofinorganics

 $\Delta V >> 0$ 

 $\Delta V >> 0$ 





(a)

Heat

Planar binder-vapor interface (b)

Volatile Heat material

Nonplanar binder-vapor interface (c)

heating rate (T = 200 - 500°C) ≈ 0.1-1°C/min

Thermal analyses on green ceramic compacts → critical temperature range

Tape cast binder system



**Injection molding binder system** 



#### **Cold sintering of HA**





#### **Cold sintering of HA/chitosan composites**





#### **Proposed mechanisms**



 $\checkmark$ 

 $\checkmark$ 





125°C

Zinc Carboxylate	Formation constant, Log $\mathbf{k}_1$	Acid pKa	Solubility [g/100 g]	Acid Decomposition Temperature [°C]	Complex Decomposition Temperature [°C]
Zinc Acetate	0.88 [30]	4.76 [31]	40 [35]	230 [36]	240–271 [37]
Zinc Citrate	4.93 [30]	3.13 [31]	40 [35]	165 [38]	300–400 [39]

# **Flash sintering**

#### **Discovered in 2010**

(accidentally... during experiments on Amperometer *field effect on grain growth)* Voltmeter Power supply Furnace Electrodes electric field  $\bigcirc \bigcirc \bigcirc \bigcirc \bigcirc \bigcirc \bigcirc$ ′Ø current flow LVDT  $\bigcirc$ through the green Sample ′⊘⊘⊘⊘ *compact* Thermocouple Sample Furnace CCD camera

### sintering in just few seconds

(combination of T and E) thermal runaway of Joule heating

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#### Phenomenology



speed = 4x

#### **Stages and fingerprints**





**Stage II "flash event"** thermal runaway

Stage III at J<sub>max</sub>

stationary condition



- Sintering  $\equiv$  Resisitivity drop  $\equiv$  Very rapid heating ( $\approx 10^3 \cdot 10^4$  K/min)
- Bright light emission («flash»)
- A minimum conductivity is needed to produce the flash
- The onset temperature descreases with the applied field



Thermal runaway for Joule heating

#### Ceramics with negative temperature coefficient (NTC) for electrical resistivity





#### **Electric field and onset temperature**









Useful defective structure from the high heating rate

Chemical reactivity (CH<sub>4</sub> oxidation) of  $La_{0.1}Sr_{0.9}TiO_3$ 









# **Ultra-fast High-temperature Sintering (UHS)**

#### Proposed in 2020



argon atmosphere



- Very high heating rates
- Possiblility to achieve 'very high' temperature
- Simple equipment (<10 k€)
- Small components
- Reducing conditions

#### Typical UHS Process for LLZTO

Heating rate: ~20,000 C/min Sintering: ~6 s at ~1,500 C.

#### **UHS of YSZ nanopowders**





#### UHS of 3D printed BaTiO<sub>3</sub> bodies



#### Very high heating rate effects

#### **Enhanced densification**

- Reduced coarsening / densification rate ratio
- Non-equilibrium grain boundaries?





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